



Introduction to VLSI Design

[Adapted from Rabaey's *Digital Integrated Circuits*, ©2002, J. Rabaey et al.]

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Design Metrics

- How to evaluate performance of a digital circuit (gate, block, ...)?
 - » Cost
 - » Reliability
 - » Scalability
 - » Speed (delay, operating frequency)
 - » Power dissipation
 - » Energy to perform a function

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Cost of Integrated Circuits

- NRE (non-recurrent engineering) costs
 - » design time and effort, mask generation
 - » one-time cost factor
- Recurrent costs
 - » silicon processing, packaging, test
 - » proportional to volume
 - » proportional to chip area

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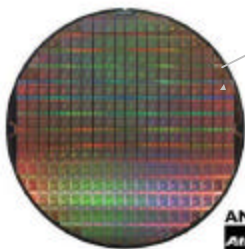
NRE Cost is Increasing



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Die Cost



Single die

Wafer



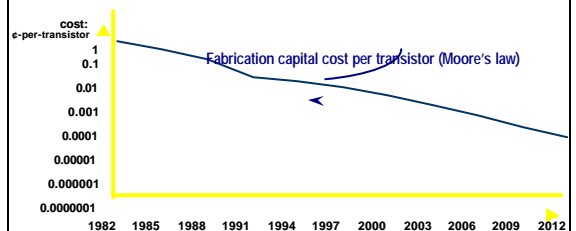
Going up to 12" (30cm)

From <http://www.amd.com>

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Cost per Transistor



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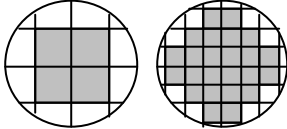


Yield

$$Y = \frac{\text{No. of good chips per wafer}}{\text{Total number of chips per wafer}} \times 100\%$$

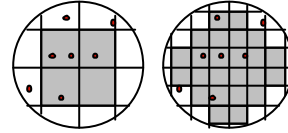
$$\text{Die cost} = \frac{\text{Wafer cost}}{\text{Dies per wafer} \times \text{Die yield}}$$

$$\text{Dies per wafer} = \frac{\pi \times (\text{wafer diameter}/2)^2}{\text{die area}} = \frac{\pi \times \text{wafer diameter}}{\sqrt{2} \times \text{die area}}$$



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Defects



$$\text{die yield} = \left(1 + \frac{\text{defects per unit area} \times \text{die area}}{\alpha} \right)^{-\alpha}$$

α is approximately 3

$$\text{die cost} = f(\text{die area})^4$$

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Some Examples (1994)

| Chip | Metal layers | Line width | Wafer cost | Def./cm ² | Area mm ² | Dies/wafer | Yield | Die cost |
|--------------|--------------|------------|------------|----------------------|----------------------|------------|-------|----------|
| 386DX | 2 | 0.90 | \$900 | 1.0 | 43 | 360 | 71% | \$4 |
| 486 DX2 | 3 | 0.80 | \$1200 | 1.0 | 81 | 181 | 54% | \$12 |
| Power PC 604 | 4 | 0.80 | \$1700 | 1.3 | 121 | 115 | 28% | \$53 |
| HP PA 7100 | 3 | 0.80 | \$1300 | 1.0 | 196 | 66 | 27% | \$73 |
| DEC Alpha | 3 | 0.70 | \$1500 | 1.2 | 234 | 53 | 19% | \$149 |
| Super Sparc | 3 | 0.70 | \$1700 | 1.6 | 256 | 48 | 13% | \$272 |
| Pentium | 3 | 0.80 | \$1500 | 1.5 | 296 | 40 | 9% | \$417 |

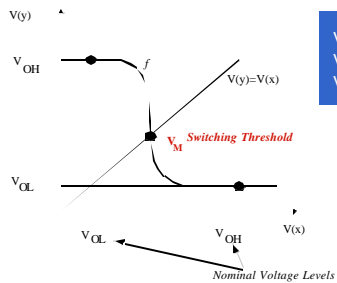
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Reliability? Noise in Digital Integrated Circuits



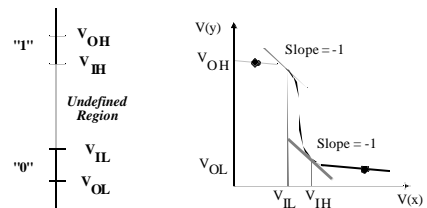
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DC Operation Voltage Transfer Characteristic



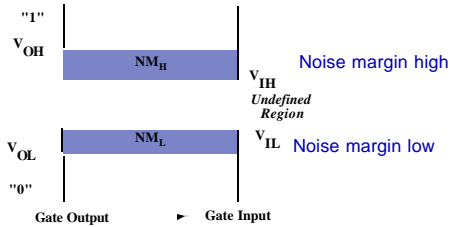
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Mapping between analog and digital signals



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Definition of Noise Margins



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Noise Budget

- Allocates gross noise margin to expected sources of noise
- Sources: supply noise, cross talk, interference, offset
- Differentiate between fixed and proportional noise sources

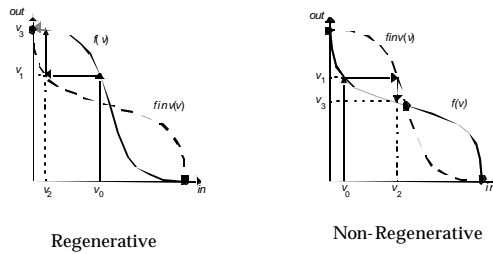
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Key Reliability Properties

- Absolute noise margin values are deceptive
 - » a floating node is more easily disturbed than a node driven by a low impedance (in terms of voltage)
- Noise immunity is the more important metric – **the capability to suppress noise sources**
- Key metrics: Noise transfer functions, Output impedance of the driver and input impedance of the receiver;

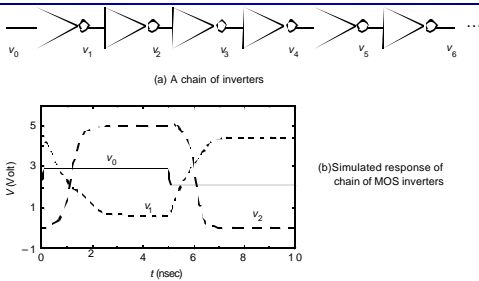
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Regenerative Property



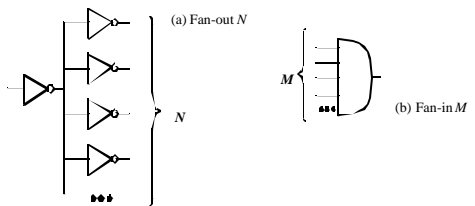
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Regenerative Property



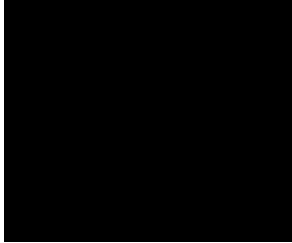
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Fan-in and Fan-out



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The Ideal Gate



$$R_i = \infty$$

$$R_o = 0$$

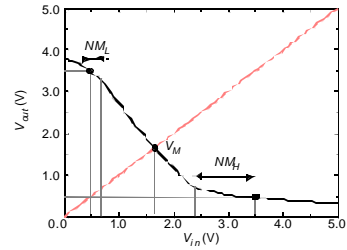
$$\text{Fanout} = \infty$$

$$NM_H = NM_L = V_{DD}/2$$

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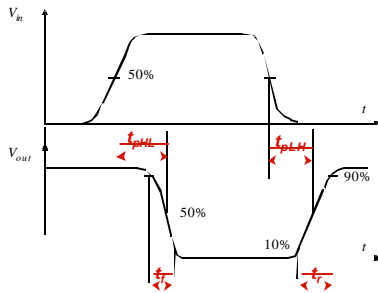
An Old-time Inverter



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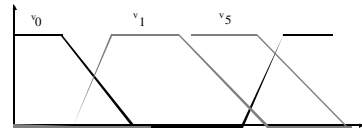
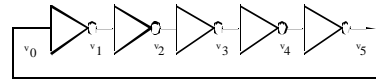
Delay Definitions



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Ring Oscillator

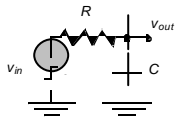


$$T = 2 \times t_p \times N$$

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A First-Order RC Network



$$v_{out}(t) = (1 - e^{-t/\tau}) V$$

$$t_p = \ln(2) \tau = 0.69 RC$$

Important model - matches delay of inverter

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Power Dissipation

Instantaneous power:

$$p(t) = v(t)i(t) = V_{supply}i(t)$$

Peak power:

$$P_{peak} = V_{supply}i_{peak}$$

Average power:

$$P_{ave} = \frac{1}{T} \int_t^{t+T} p(t) dt = \frac{V_{supply}}{T} \int_t^{t+T} i_{supply}(t) dt$$

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Energy and Energy-Delay

Power-Delay Product (PDP) =

$$E = \text{Energy per operation} = P_{av} \cdot t_p$$

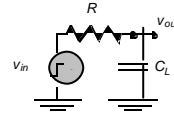
Energy-Delay Product (EDP) =

$$\text{quality metric of gate} = E \cdot t_p$$

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A First-Order RC Network



$$E_{0 \rightarrow 1} = \int_0^T P(t) dt = V_{dd} \int_0^T i_{supply}(t) dt = V_{dd} \int_0^T C_L dV_{out} = C_L \cdot V_{dd}^2$$

$$E_{cap} = \int_0^T P_{cap}(t) dt = \int_0^T V_{out} i_{cap}(t) dt = \int_0^T C_L V_{out} dV_{out} = \frac{1}{2} C_L \cdot V_{dd}^2$$

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Summary

- Digital integrated circuits have come a long way and still have quite some potential left for the coming decades
- Some interesting challenges ahead
 - » Getting a clear perspective on the challenges and potential solutions is the purpose of this book
- Understanding the design metrics that govern digital design is crucial
 - » Cost, reliability, speed, power and energy dissipation

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